

ABSTRACT OF THE DISCLOSURE

In the past, a power supply distance between a power source and an LSI package could not be shortened and power supply variations could easily produce an adverse effect.

In the present invention, a power supply module is mounted on the surface of an LSI package.

The power supply distance between the LSI and power supply module can be shortened. As a result, the power source noise can be reduced, the efficiency and response rate of the power source unit are high, and the generated electromagnetic field can be reduced.

Moreover, since each LSI package has a power supply module required therefor, the number of required power source types (voltage types) on the substrate with the package mounted thereon can be decreased. As a result, the mounting efficiency can be increased and the substrate can be manufactured at a low cost.